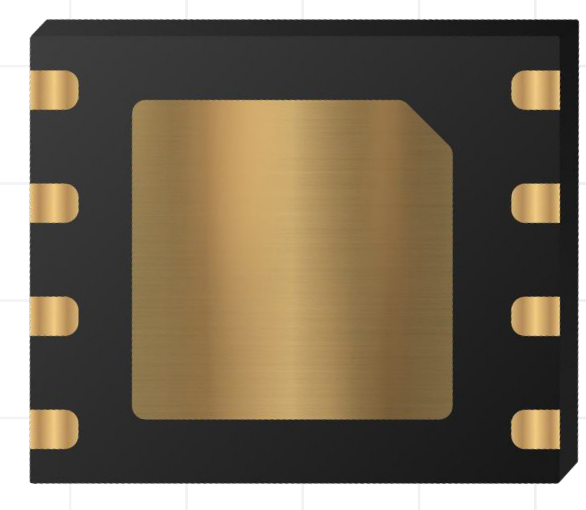
Hologram

Embedded (eSIM) format



Hyper eUICC SIM

Hyper eUICC SIM – Embedded (eSIM) format

Product overview

A secure, device-agnostic IoT embedded SIM card for global deployments built for M2M data, with easy activation, transparent pricing, and developer-friendly tools. Hologram's Hyper SIMs use an eUICC OS to remotely update coverage over-the-air by adding or removing connectivity profiles, without requiring you to swap the SIM in your device. Network fallback functionality can dynamically switch profiles in the event that a profile loses connectivity.

Primary part number

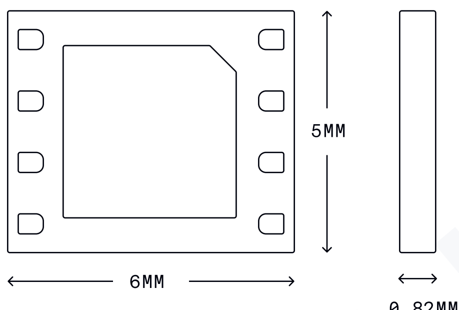
G3-DFN8

Network availability

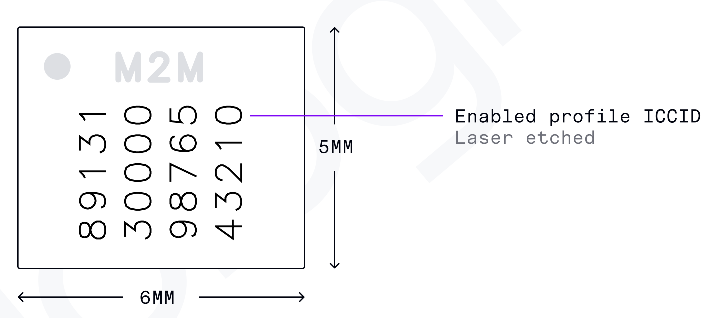
Works globally with Hologram's 2G through 5G network including LTE-M and NB-IoT where coverage is available. More information: https://www.hologram.io/pricing/coverage

Mechanical specifications

Bottom view

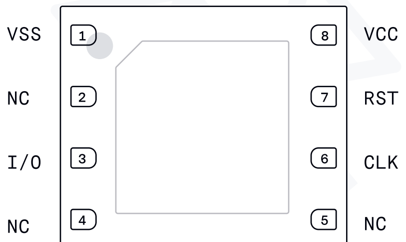


Top view



Physical characteristics

Top view



Size

MFF2 (DFN8)	Embedded SIM	6 × 5 × 0.82 mm

Pin definitions

1	VSS	Voltage Source Supply
2	NC	No Connect
3	I/O	Input/Output
4	NC	No Connect
5	NC	No Connect
6	CLK	Clock
7	RST	Reset
8	VCC	Input Voltage

Hardware features

Chip type

Supplier	Infineon
Chip Code	SLM17ECB800B

Electrical

Operating Voltage	1.62V to 5.5V

Hardware characteristics

Grade	Industrial
Operational Temperature	−40°C to +105°C
Data Retention	10 years @ 25°C
Write Endurance	>1.5M cycles
Memory (NVM)	330 KB
Memory (SRAM)	20 KB

AC electrical parameters standards

ETSI 3GPP TS 102 221 v16.0.0 - Smart Cards; UICC-Terminal interface; Physical and logical characteristics
ISO/IEC 7816, T=0 standard for Cards with contacts — USB electrical interface and operating procedures

Compliance

Chip	Common Criteria	EAL 4+ PP-0084 (chipset) Certificate: BSI-DSZ-CC-1126-V2-2021
OS	GSMA	SGP.01 Embedded SIM Remote Provisioning Architecture v4.2 SGP.02 Embedded UICC Technical Specification v4.2 SGP.16 M2M Compliance Process v1.3
	TCA Trusted Connectivity Alliance	SIMalliance eUICC Profile Package Interoperable Format Technical Specification v2.3.1
	GlobalPlatform	Card Specification Version 2.3.1 Card Specification Amendments A, B, D & E
Software	Oracle Java Card	Java Card 3 Platform, Classic Edition version 3.0.5
	3GPP A Global Initiative	Release 16
Remote SIM provisioning	GSMA	SGP.01 Embedded SIM Remote Provisioning Architecture v4.2 SGP.02 Embedded UICC Technical Specification v4.2 SGP.16 M2M Compliance Process v1.3
Supplier's Declaration of Conformity		Manufactured according to the following standards: • RoHS 2015/863/EU • Reach certification • GSMA SAS-UP • ISO 9001:2015 • ISO 27001 • ISO 14001

Part numbers

Active part numbers	Past part numbers
G3-DFN8	G3-F-DFN8
G3-G2-DFN8	G3-G2-F-DFN8
G2-F-DFN8	GL2-AFB-MFF2
US2+-G2-F-DFN8	GL2-USA2+-AFB-MFF2
US2M-G2-F-DFN8	GL2-USA2M-AFB-MFF2
CA1-G2-F-DFN8	—

Multipack labeling

Single SIM: `G3-DFN8`
10-pack: `G3-DFN8`-10
100-pack: `G3-DFN8`-100
1000-pack: `G3-DFN8`-1000

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